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Silicon PNP Epitaxial

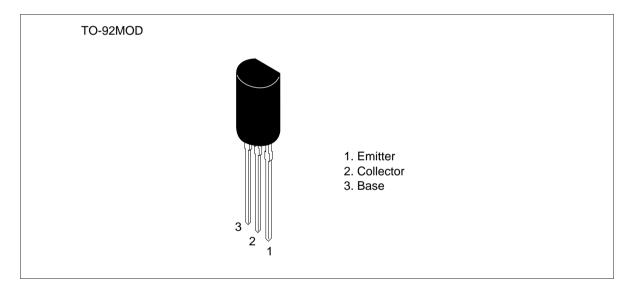


ADE-208-1024 (Z) 1st. Edition Mar. 2001

Application

- Low frequency power amplifier
- Complementary pair with 2SD468

Outline



Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item	Symbol	Ratings	Unit
Collector to base voltage	V _{CBO}	-25	V
Collector to emitter voltage	V _{CEO}	-20	V
Emitter to base voltage	V _{EBO}	-5	V
Collector current	I _c	-1.0	А
Collector peak current	İ _{C(peak)}	-1.5	A
Collector power dissipation	Pc	0.9	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Electrical Characteristics (Ta = 25°C)

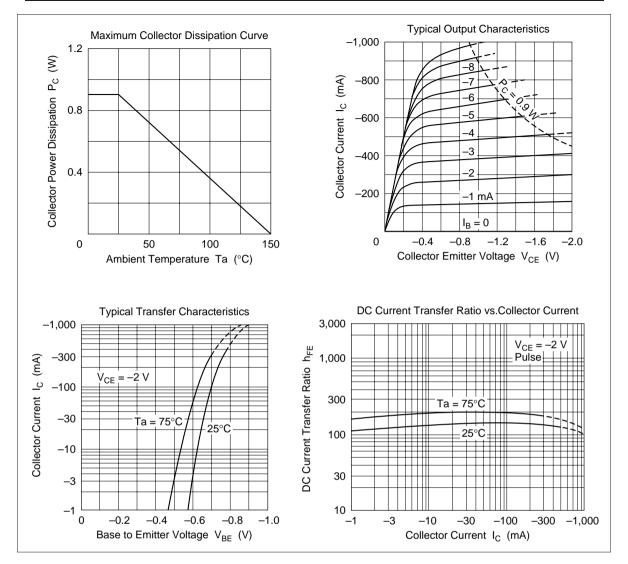
Item	Symbol	Min	Тур	Мах	Unit	Test conditions
Collector to base breakdown voltage	$V_{(\text{BR})\text{CBO}}$	-25	_	_	V	$I_{c} = -10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(\text{BR})\text{CEO}}$	-20	_	_	V	$I_c = -1 \text{ mA}, \text{ R}_{BE} = \infty$
Emitter to base breakdown voltage	$V_{\rm (BR)EBO}$	-5	—	—	V	$I_{\rm E} = -10 \ \mu A, \ I_{\rm C} = 0$
Collector cutoff current	I _{CBO}	_	_	-1.0	μΑ	$V_{CB} = -20 \text{ V}, \text{ I}_{E} = 0$
DC current transfer ratio	$h_{\rm FE}^{*1}$	85	_	240		$V_{CE} = -2 V,$ $I_{C} = -0.5 A (Pulse test)$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	-0.2	-0.5	V	$I_{\rm c} = -0.8 \text{ A},$ $I_{\rm B} = -0.08 \text{ A}$ (Pulse test)
Base to emitter voltage	V_{BE}	_	-0.8	-1.0	V	$V_{CE} = -2 V,$ $I_{C} = -0.5 A (Pulse test)$
Gain bandwidth product	f _T	—	350	—	MHz	$V_{ce} = -2 V,$ $I_c = -0.5 A (Pulse test)$
Collector output capacitance	Cob	_	38		pF	$V_{CB} = -10 \text{ V}, I_{E} = 0$ f = 1 MHz

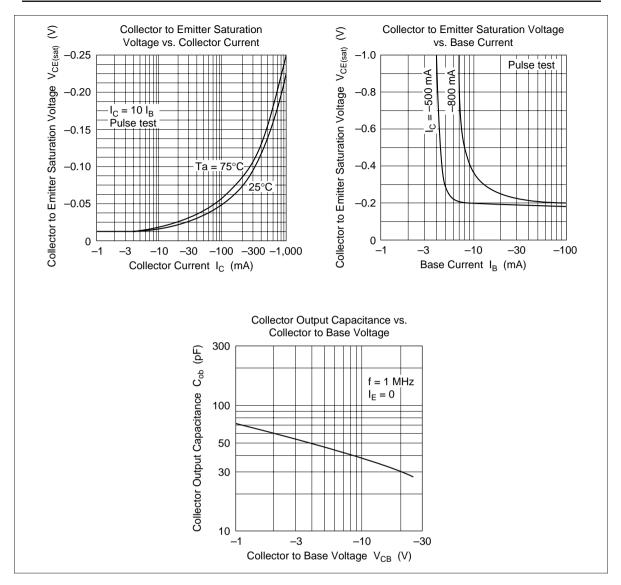
Note: 1. The 2SB562 is grouped by $h_{\mbox{\tiny FE}}$ as follows. С

В

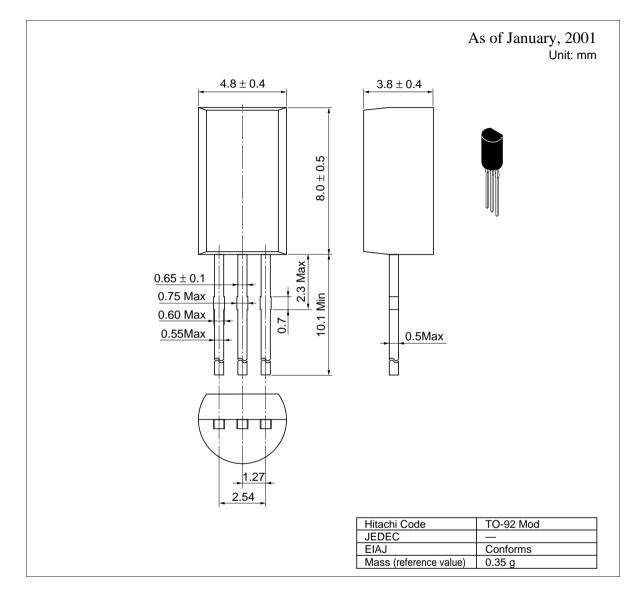
120 to 240 85 to 170







Package Dimensions



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